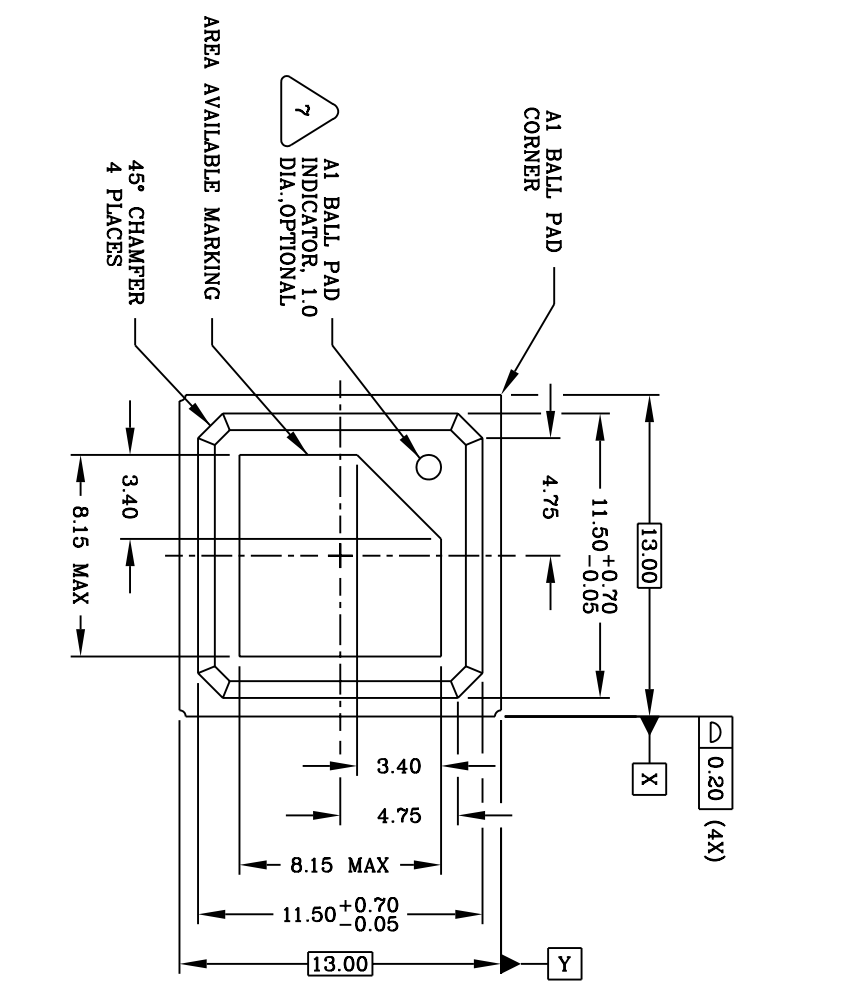
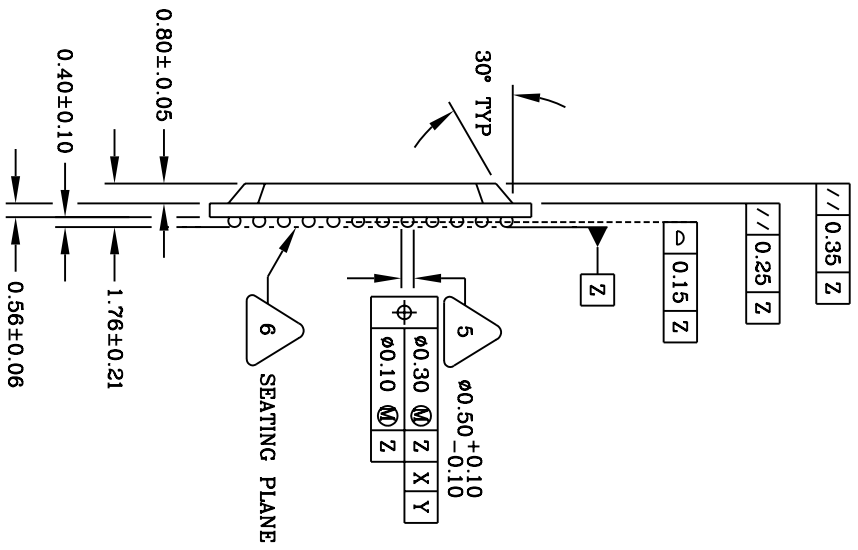


REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
01	ADD "GREEN" BBG NOMENCLATURE	10/19/04	TU YU	



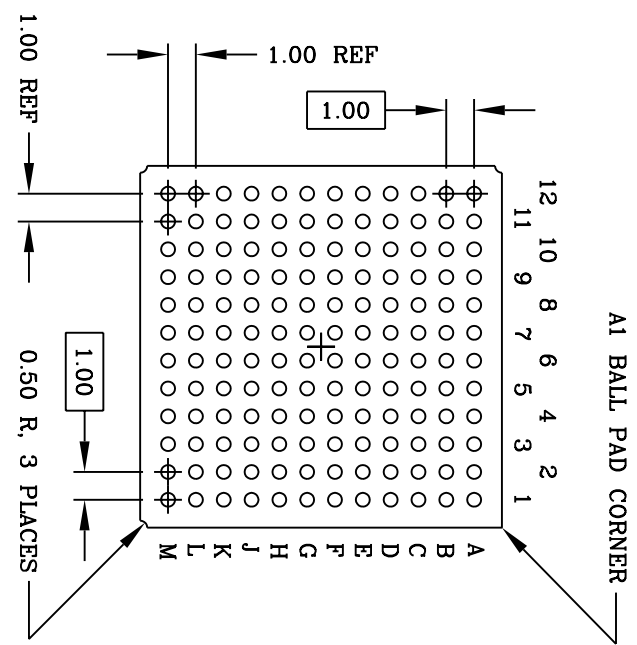
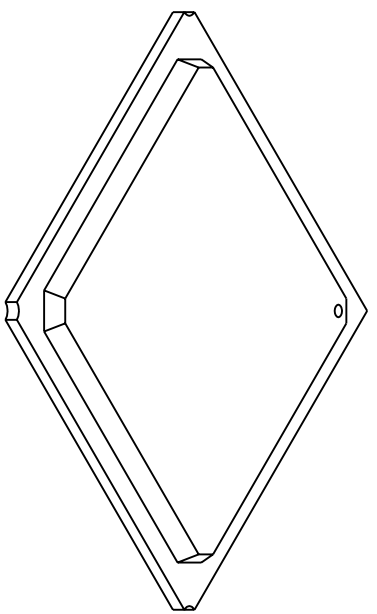
TOP VIEW



SIDE VIEW

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS X.XX ±0.10 X.XXX ±0.05 X.XXX ±0.03		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS ANGULAR ET		Integrated Device Technology, Inc. 2975 Slender Way, Santa Clara, CA 95054 (408) 727-6116 FAX (408) 492-8074 WWW.IDT.COM	
APPROVALS	DATE	TITLE:			
DRAWN <i>pkp</i>	07/13/00	BB/BBG 144 PACKAGE OUTLINE			
CHECKED		13.0 X 13.0 mm BODY PBGA			
		DRAWING No.	SIZE	SCALE	REV
		PSC-4094	C	N/A	01
DO NOT SCALE DRAWING					
SHEET 1 OF 3					

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
01	ADD "GREEN"	BBG NOMENCLATURE	10/19/04	TU VU



BOTTOM VIEW
(144 SOLDER BALLS)

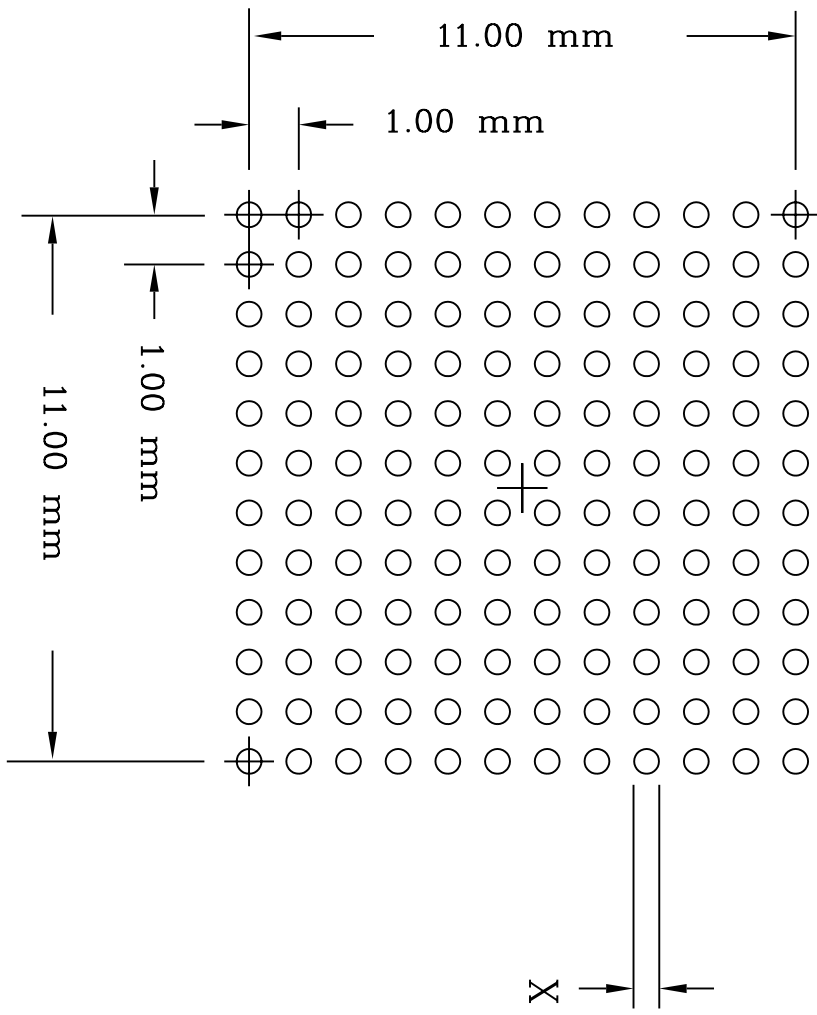
8. REFERENCE SPECIFICATIONS:
 A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 B. AAWW SPEC #001-0519-2062: MARKING.
 C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MO-151/B, VARIATION AAE-1 FOR 1.00mm PITCH AND VARIATION BAE-1 FOR 1.27mm PITCH.
7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK. AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 144.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 12 X 12.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		APPROVALS		DATE	
XXX.XXX	XXX.XXX	DRAWN	DATE	07/13/00	
XXX.XXX	XXX.XXX	CHECKED			
IDT Integrated Device Technology, Inc. www.IDT.com 2975 Slender Way, Santa Clara, CA 95054 (408) 727-6116 FAX (408) 492-8074					
TITLE: BB/BBG 144 PACKAGE OUTLINE					
DRAWING No. PSC-4094					
DO NOT SCALE DRAWING					
SIZE	SCALE	REV			
C	N/A	01			

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADD "GREEN" BPG NOMENCLATURE	10/19/04	TU YU

LAND PATTERN DIMENSIONS



SYMBOL	MIN	NOM	MAX
X	.35	.40	.45

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS X.XX ±0.08 X.XXX ±0.03		ANGULAR ±1°	
APPROVALS	DATE	DATE	
DRAWN <i>pjp</i>	07/13/00	BB/BBG 144 PACKAGE OUTLINE 13.0 X 13.0 mm BODY PBGA	
CHECKED		DRAWING No. PSC-4094	
		SIZE	SCALE
		C	N/A
		REV	01
DO NOT SCALE DRAWING			
SHEET 3 OF 3			

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 www.IDT.com 2975 Slender Way, Santa Clara, CA 95054
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